[Claim 1] A method for preparing a liquid chemical kit for forming a water-repellent protective film, the liquid chemical kit being for forming a water-repellent protective film at the time of cleaning a wafer having at its surface an uneven pattern and containing silicon element at least at a part of the uneven pattern at least on surfaces of recessed portions of the uneven pattern, the liquid chemical kit comprising a treatment liquid (A) that contains a nonaqueous organic solvent and a silylation agent and a treatment liquid (B) that contains a nonaqueous organic solvent, and an acid or base, the method being characterized by comprising:

a dehydrating step for adjusting a water content of the nonaqueous organic solvent to 200 mass ppm or less;

a step of producing the treatment liquid (A), wherein the nonaqueous organic solvent and the silylation agent are mixed after the dehydrating step; and

a step of producing the treatment liquid (B), wherein the nonaqueous organic solvent and the acid or base are mixed after the dehydrating step.

[Claim 2] A method for preparing a liquid chemical kit for forming a water-repellent protective film, as claimed in claim 1, characterized in that the dehydrating step is at least one selected from the group consisting of a step of

independently represents a monovalent functional group of which element to be bonded to a silicon element is nitrogen, the monovalent functional group optionally containing a fluorine element or a silicon element. e is an integer of from 1 to 3. f is an integer of from 0 to 2. The total of e and f is 1 to 3.].

[Claim 9] A method for preparing a liquid chemical for forming a water-repellent protective film, which is characterized in that the treatment liquid (A) and the treatment liquid (B) of the liquid chemical kit for forming a water-repellent protective film, which has been prepared by a method for preparing a liquid chemical kit for forming a water-repellent protective film as claimed in any of claims 1 to 8, are mixed together.

[Claim 10] A method for cleaning a wafer having at its surface an uneven pattern and containing silicon element at least at a part of the uneven pattern, which is characterized by using a liquid chemical for forming a water-repellent protective film, which has been prepared by mixing together the treatment liquid (A) and the treatment liquid (B) of the liquid chemical kit for forming a water-repellent protective film, which has been prepared by a method for preparing a liquid chemical kit for forming a water-repellent protective film as claimed in any of claims 1 to 8.